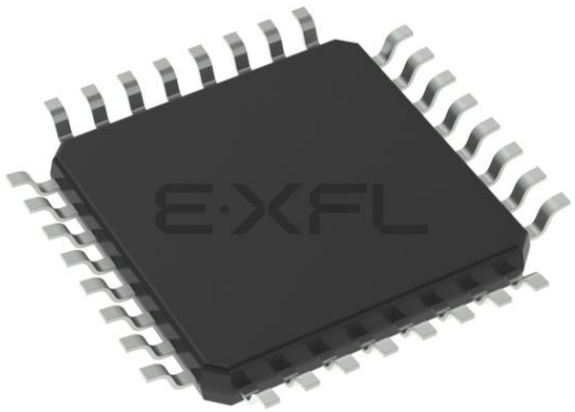

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	AVR
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	27
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	32-TQFP
Supplier Device Package	32-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atmega3208-afr

        - SleepWalking peripherals
    - Power Down with limited wake-up functionality
- Peripherals
    - One 16-bit Timer/Counter type A with dedicated period register, three compare channels (TCA)
    - Three 16-bit Timer/Counter type B with input capture (TCB)
    - One 16-bit Real Time Counter (RTC) running from external crystal or internal RC oscillator
    - Three USART with fractional baud rate generator, autobaud, and start-of-frame detection
    - Master/slave Serial Peripheral Interface (SPI)
    - Dual mode Master/Slave TWI with dual address match
        - Standard mode (Sm, 100 kHz)
        - Fast mode (Fm, 400 kHz)
        - Fast mode plus (Fm+, 1 MHz)
    - Event System for CPU independent and predictable inter-peripheral signaling
    - Configurable Custom Logic (CCL) with up to four programmable Lookup Tables (LUT)
    - One Analog Comparator (AC) with scalable reference input
    - One 10-bit 150 ksps Analog to Digital Converter (ADC)
    - Five selectable internal voltage references: 0.55V, 1.1V, 1.5V, 2.5V, and 4.3V
    - CRC code memory scan hardware
        - Optional automatic scan after reset
    - Watchdog Timer (WDT) with Window Mode, with separate on-chip oscillator
    - External interrupt on all general purpose pins
- I/O and Packages:
    - 27 programmable I/O lines
    - 32-pin VQFN 5x5 and TQFP 7x7
- Temperature Range: -40°C to 125°C
- Speed Grades:
    - 0-5 MHz @ 1.8V – 5.5V
    - 0-10 MHz @ 2.7V – 5.5V
    - 0-20 MHz @ 4.5V – 5.5V, -40°C to 105°C

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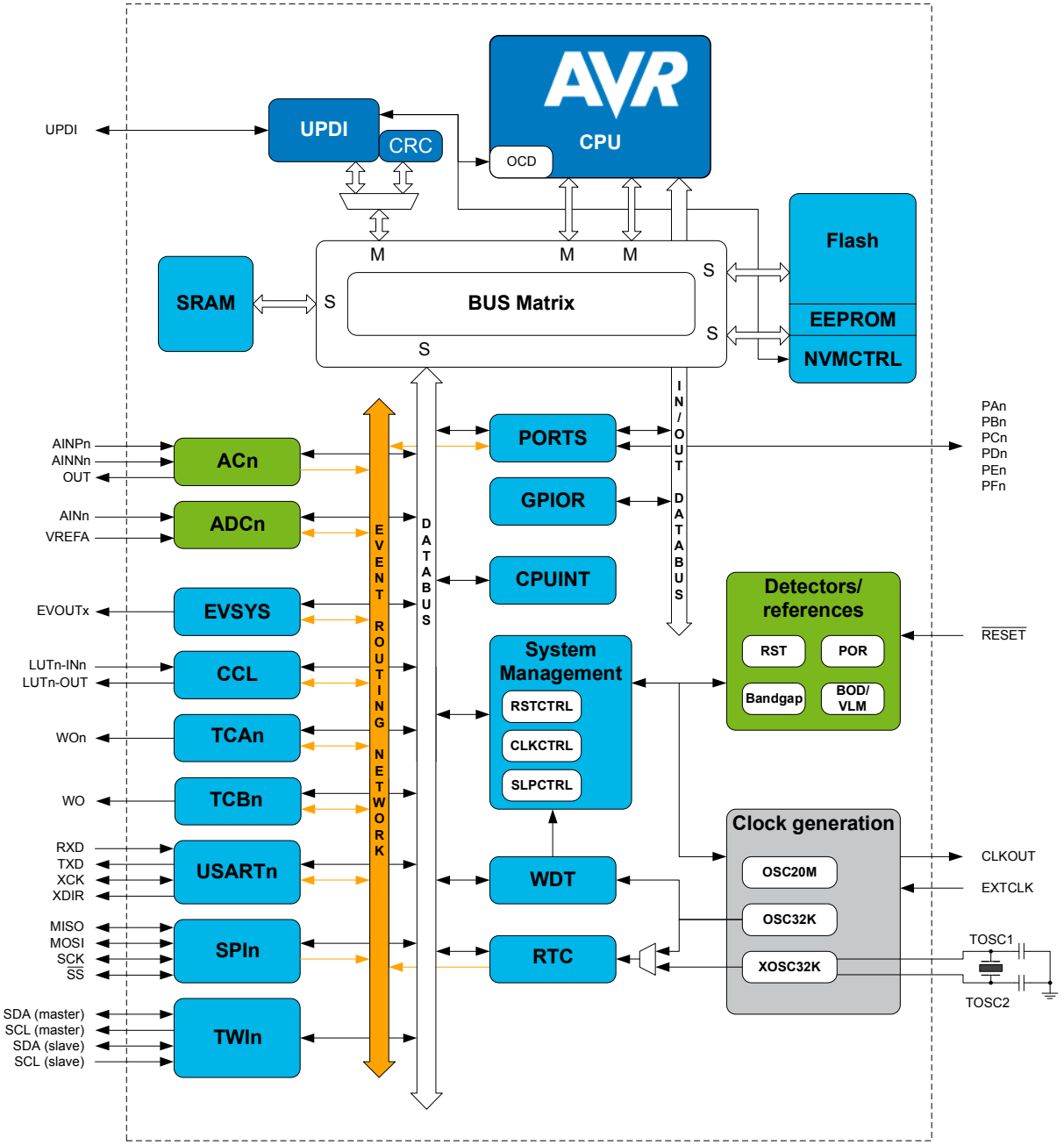
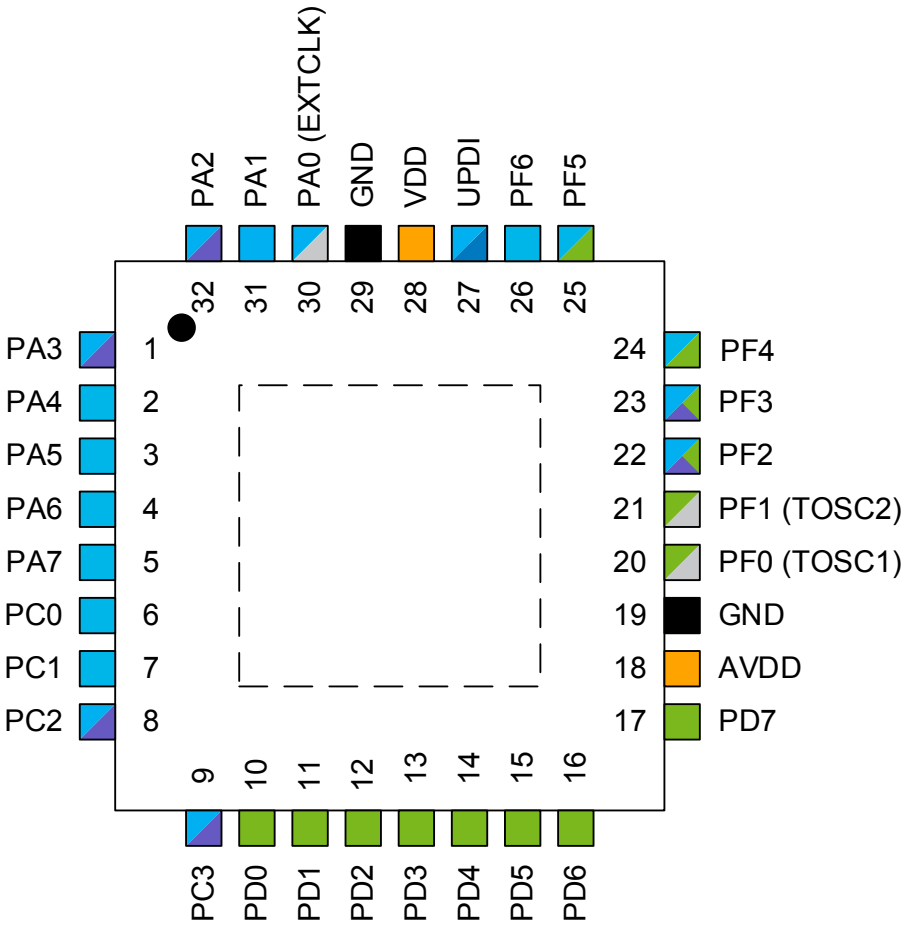
2. Block Diagram



3. Pinout

3.1 32-pin QFN/TQFP



Power

- Input supply
- Ground
- GPIO on VDD power domain
- GPIO on AVDD power domain

Functionality

- Programming, debug
- Clock, crystal
- TWI
- Digital functions only
- Analog functions

Table 5-21. Clock and Timing Characteristics

Symbol	Description	Conditions	Min.	Typ.	Max.	Unit
f_{ADC}	Sample rate	1.1V≤V_{REF}	15	-	115	ksps
		1.1V≤V_{REF} (8-bit resolution)	15	-	150	
		V_{REF}=0.55V (10 bits)	7.5	-	20	
CLK_{ADC}	Clock frequency	V_{REF}=0.55V (10 bits)	100	-	260	kHz
		1.1V≤V_{REF} (10 bits)	200	-	1500	
		1.1V≤V_{REF} (8-bit resolution)	200	-	2000	
Ts	Sampling time		2	2	33	CLK_{ADC} cycles
T_{CONV}	Conversion time (latency)	Sampling time = 2 CLK_{ADC}	8.7	-	50	µs
T_{START}	Start-up time	Internal V_{REF}	-	22	-	µs

Table 5-22. Accuracy Characteristics Internal Reference(2)

Symbol	Description	Conditions		Min.	Typ.	Max.	Unit
Res	Resolution			-	10	-	bit
INL	Integral Non-linearity	REFSEL = INTERNAL V_{REF}=0.55V	f_{ADC}=7.7 ksps	-	1.0	-	LSB
		REFSEL = INTERNAL or VDD	f_{ADC}=15 ksps	-	1.0	-	
		REFSEL = INTERNAL or VDD 1.1V≤V_{REF}	f_{ADC}=77 ksps	-	1.0	-	
			f_{ADC}=115 ksps	-	1.2	-	
DNL(1)	Differential Non-linearity	REFSEL = INTERNAL V_{REF} = 0.55V	f_{ADC}=7.7 ksps	-	0.6	-	LSB
		REFSEL = INTERNAL V_{REF} = 1.1V	f_{ADC}=15 ksps	-	0.4	-	
		REFSEL = INTERNAL or VDD 1.5V≤V_{REF}	f_{ADC}=15 ksps	-	0.4	-	
		REFSEL = INTERNAL or VDD 1.1V≤V_{REF}	f_{ADC}=77 ksps	-	0.4	-	

The accuracy characteristics numbers are based on characterization of the following input reference levels and V_{DD} ranges:

- Vref = 1.8 V, V_{DD} = 1.8 to 5.5V
- Vref = 2.6 V, V_{DD} = 2.7 to 5.5V
- Vref = 4.096 V, V_{DD} = 4.5 to 5.5V
- Vref = 4.3 V, V_{DD} = 4.5 to 5.5V

Table 5-23. Accuracy Characteristics External Reference(2)

Symbol	Description	Conditions		Min.	Typ.	Max.	Unit
Res	Resolution			-	10	-	bit
INL	Integral Non-linearity		f_{ADC}=15 ksps	-	0.9	-	LSB
			f_{ADC}=77 ksps	-	0.9	-	
			f_{ADC}=115 ksps	-	1.2	-	
DNL(1)	Differential Non-linearity		f_{ADC}=15 ksps	-	0.2	-	LSB
			f_{ADC}=77 ksps	-	0.4	-	
			f_{ADC}=115 ksps	-	0.8	-	
EABS	Absolute accuracy		f_{ADC}=15 ksps	-	2	-	LSB
			f_{ADC}=77 ksps	-	2	-	
			f_{ADC}=115 ksps	-	2	-	
EGAIN	Gain error		f_{ADC}=15 ksps	-	2	-	LSB
			f_{ADC}=77 ksps	-	2	-	
			f_{ADC}=115 ksps	-	2	-	
EOFF	Offset error			-	-0.5	-	LSB

Note:

1. A DNL error of less than or equal to 1 LSB ensures a monotonic transfer function with no missing codes.
2. These values are based on characterization and not covered by production test limits.

5.12 AC

Table 5-24. Analog Comparator Characteristics

Symbol	Description	Condition	Min.	Typ.	Max.	Unit
V_{IN}	Input Voltage	Low Power Mode	-0.2	-	V_{DD}	V
		High speed mode	-0.2	-	V_{DD}	
C_{IN}	Input Pin Capacitance	PD1 to PD6	-	3.5	-	pF
		PD7	-	14	-	

Symbol	Description	Condition	Min.	Typ.	Max.	Unit
V_{OFF}	Input Offset Voltage, Low Power Mode	0.7V<V_{IN}<(V_{DD}-0.7V)	TBD	±10	TBD	mV
		V_{IN}=[0V, V_{DD}]	-	±30	-	
	Input Offset Voltage, High-speed Mode	0.7V<V_{IN}<(V_{DD}-0.7V)	TBD	±5	TBD	
		V_{IN}=[-0.2V, V_{DD}]	-	±20	-	
I_L	Input Leakage Current		-	5	-	nA
T_{START}	Start-up Time		-	1.3	-	µs
V_{HYS}	Hysteresis, High-speed mode	HYSMODE=0x0	-	0	-	mV
		HYSMODE=0x1	-	10	-	
		HYSMODE=0x2	-	25	-	
		HYSMODE=0x3	-	50	-	
t_{PD}	Propagation Delay	25 mV Overdrive, V_{DD}≥2.7V, High speed mode	-	50	-	ns
		25 mV Overdrive, V_{DD}≥2.7V, Low Power Mode	-	150	-	

5.13 UPDI Timing

UPDI Enable Sequence

Symbol	Description	Min.	Max.	Unit
T_{RES}	Duration of Handshake/Break on RESET	10	200	µs
T_{UPDI}	Duration of UPDI.txd=0	10	200	µs
T_{Deb0}	Duration of Debugger.txd=0	0.2	1	µs
T_{DebZ}	Duration of Debugger.txd=z	200	14000	µs

6. Typical Characteristics

6.1 Power Consumption

6.1.1 Supply Currents in Active Mode

Figure 6-1. Active Supply Current vs. Frequency (1-20 MHz) at T=25°C

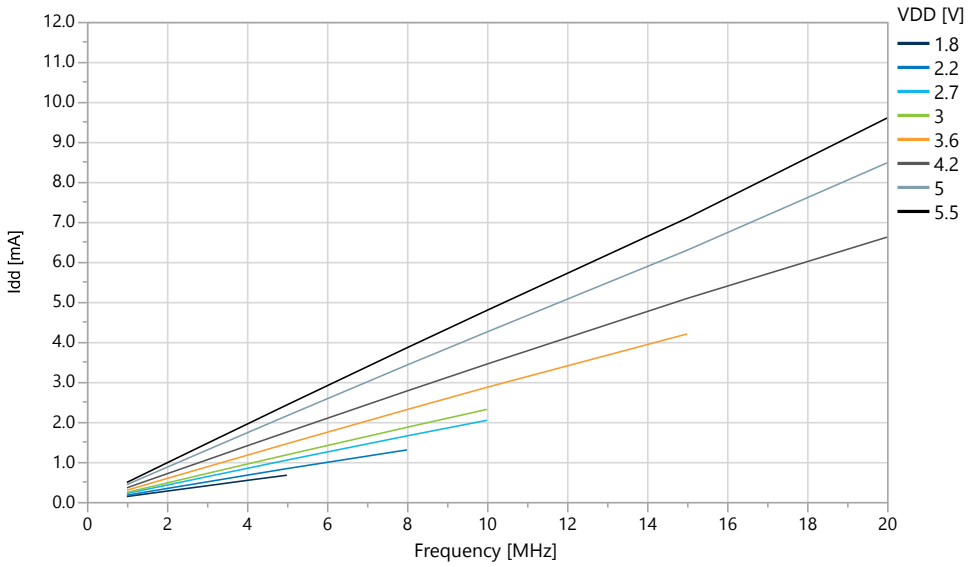


Figure 6-2. Active Supply Current vs. Frequency [0.1, 1.0] MHz at T=25°C

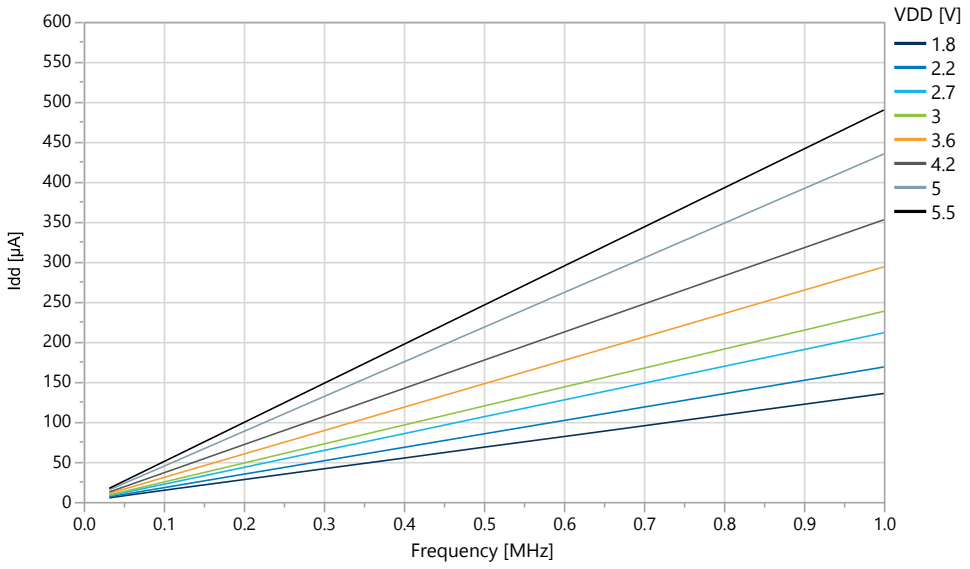
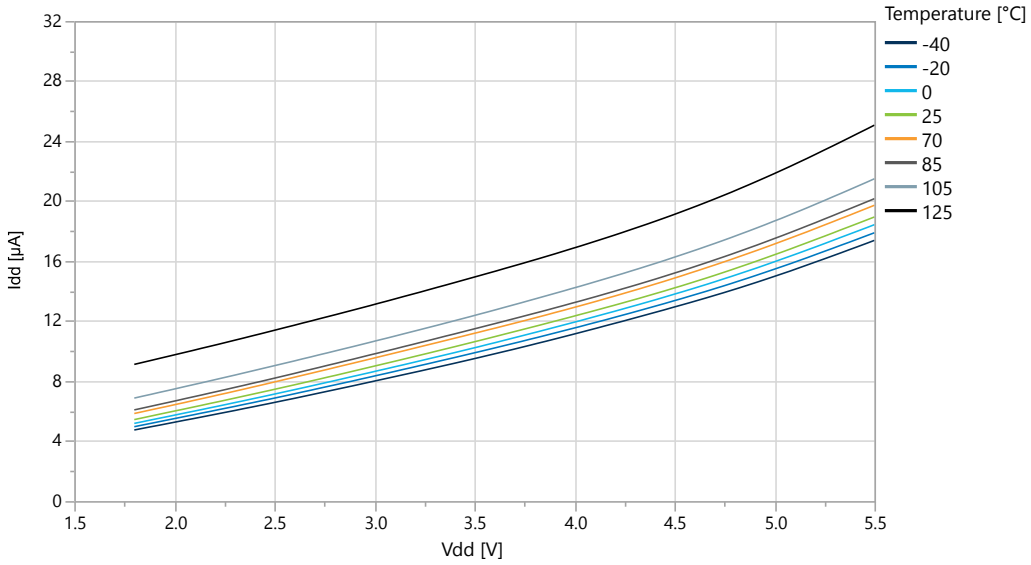
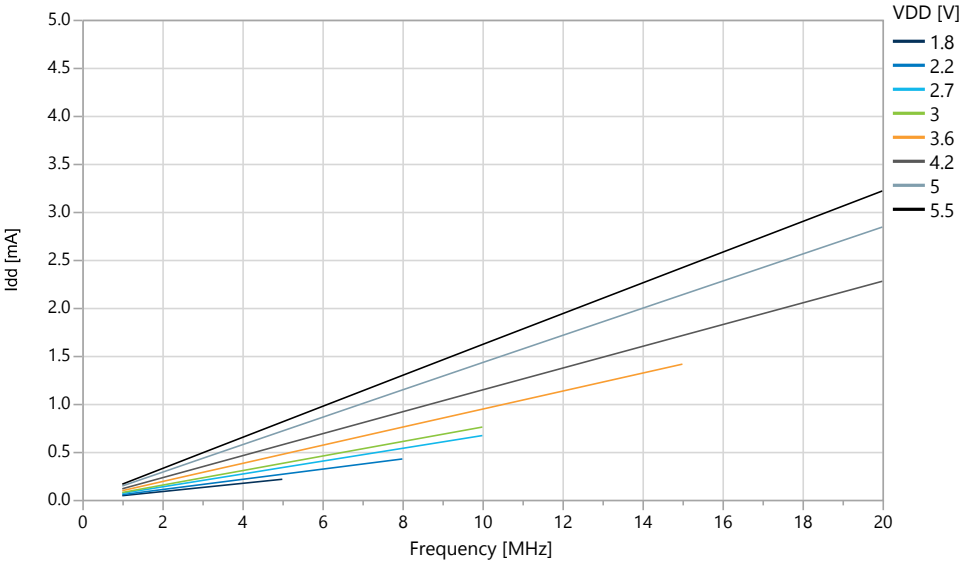


Figure 6-5. Active Supply Current vs. V_{DD} (f=32 KHz OSCULP32K)



6.1.2 Supply Currents in Idle Mode

Figure 6-6. Idle Supply Current vs. Frequency (1-20 MHz) at T=25°C



6.2 GPIO

GPIO Input Characteristics

Figure 6-17. I/O Pin Input Hysteresis vs. V_{DD}

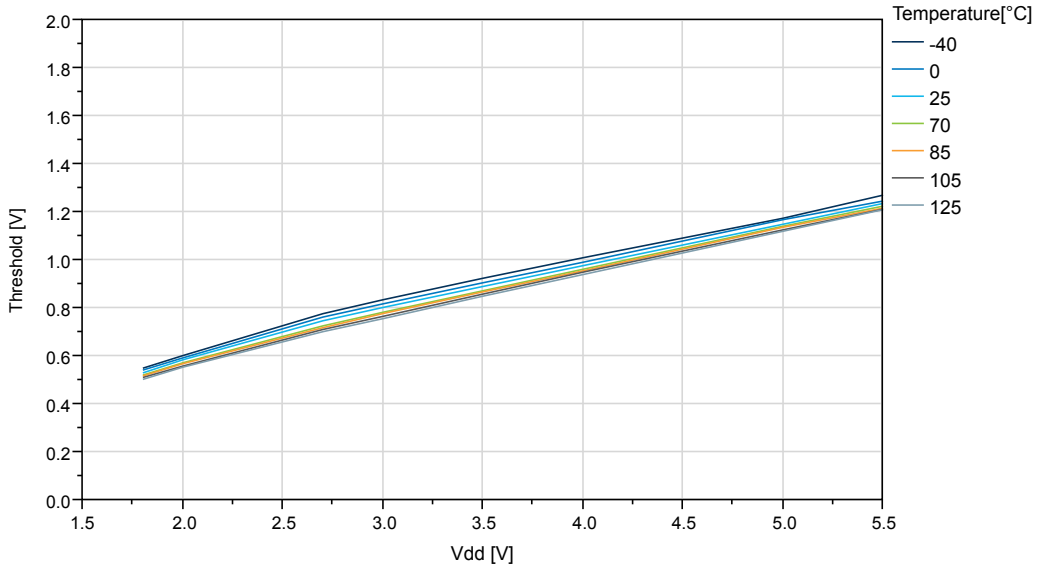


Figure 6-18. I/O Pin Input Threshold Voltage vs. V_{DD} (T=25°C)

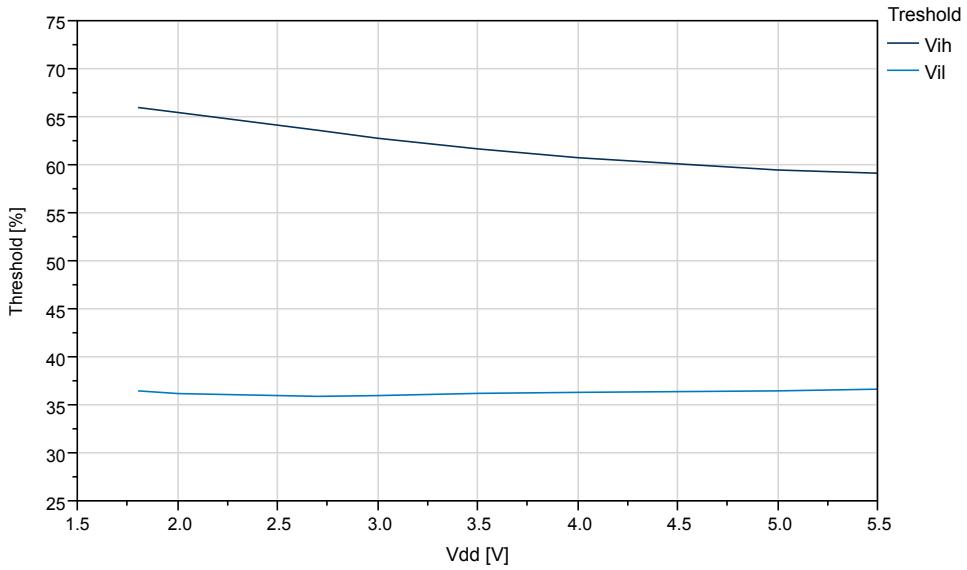


Figure 6-25. I/O Pin Output Voltage vs. Source Current (V_{DD}=1.8V)

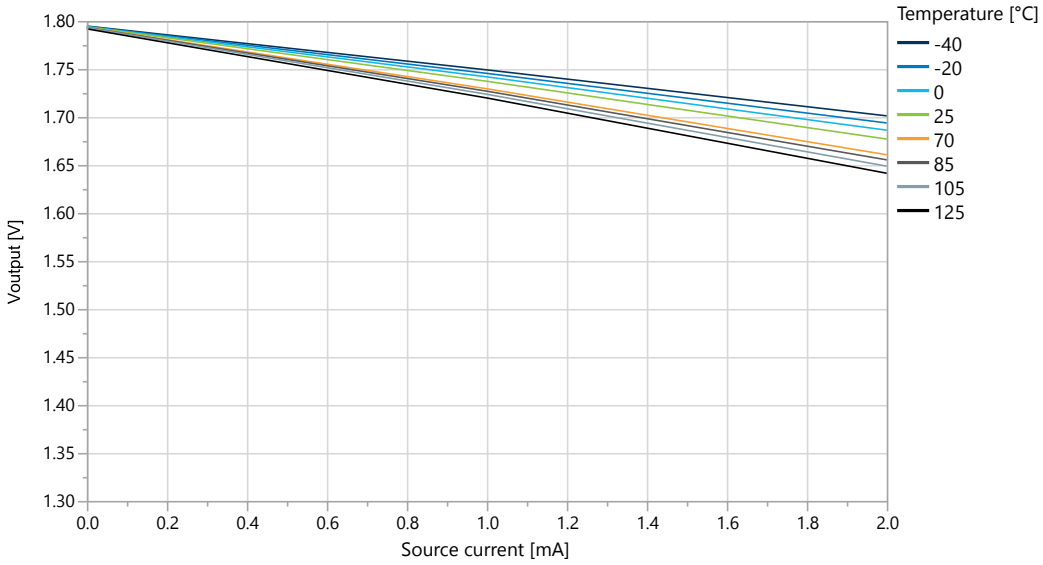


Figure 6-26. I/O Pin Output Voltage vs. Source Current (V_{DD}=3.0V)

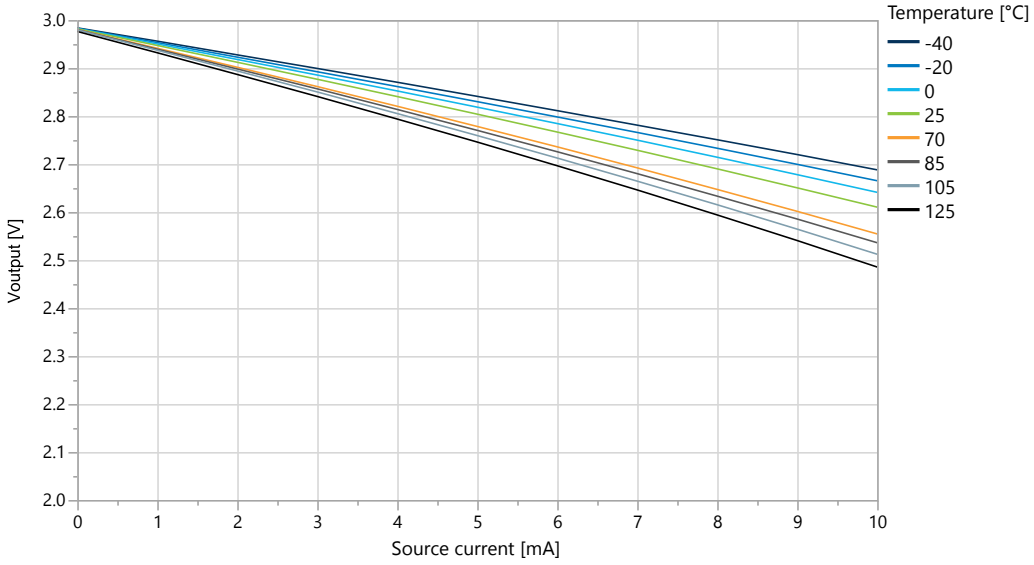


Figure 6-27. I/O Pin Output Voltage vs. Source Current (V_{DD}=5.0V)

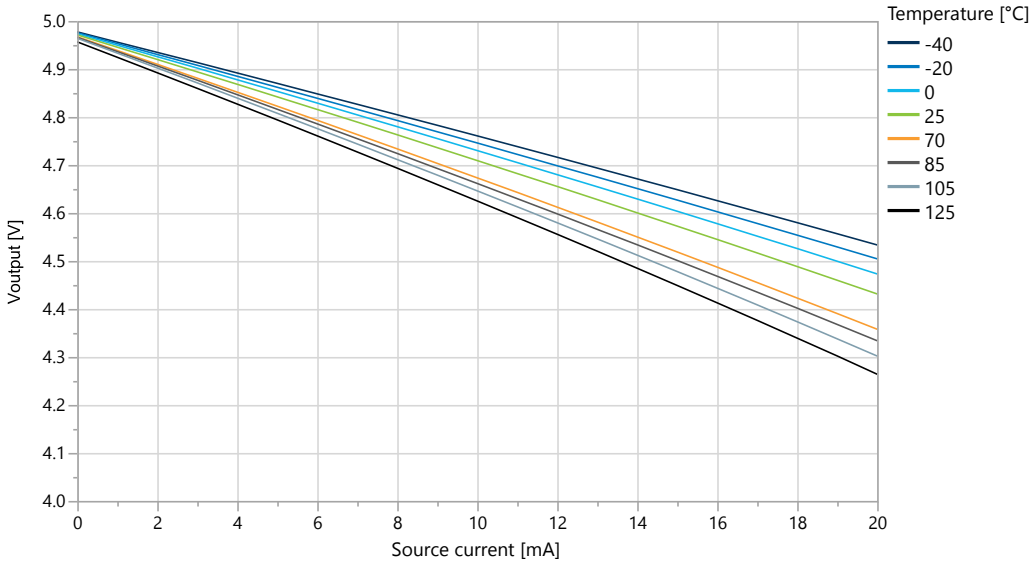
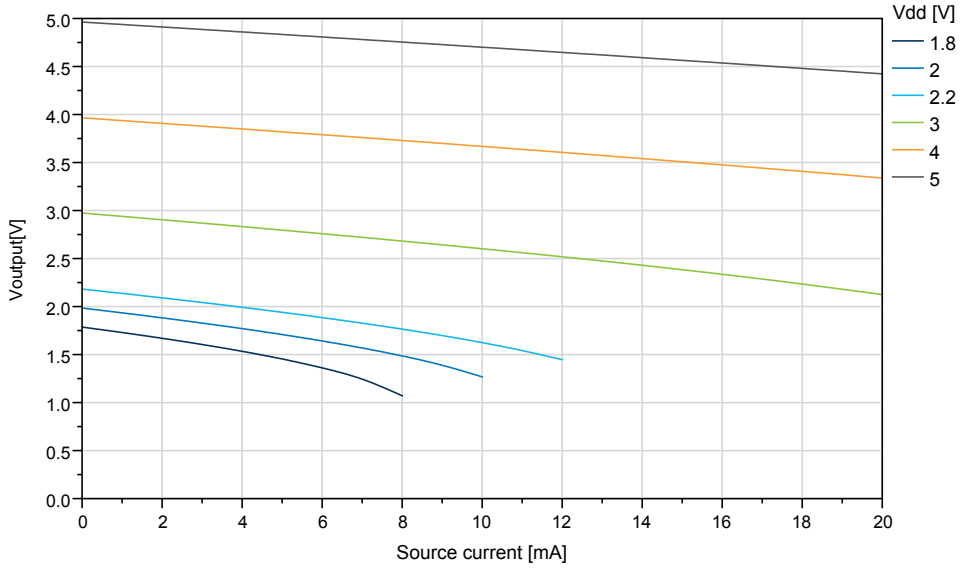


Figure 6-28. I/O Pin Output Voltage vs. Source Current (T=25°C)



GPIO Pull-Up Characteristics

Figure 6-29. I/O Pin Pull-Up Resistor Current vs. Input Voltage (V_{DD}=1.8V)

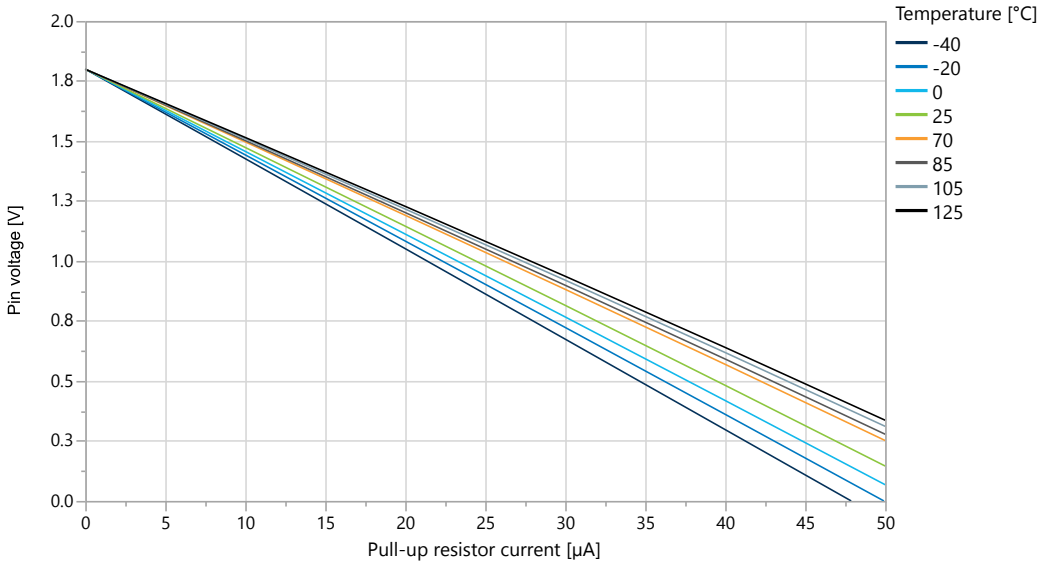


Figure 6-30. I/O Pin Pull-Up Resistor Current vs. Input Voltage (V_{DD}=3.0V)

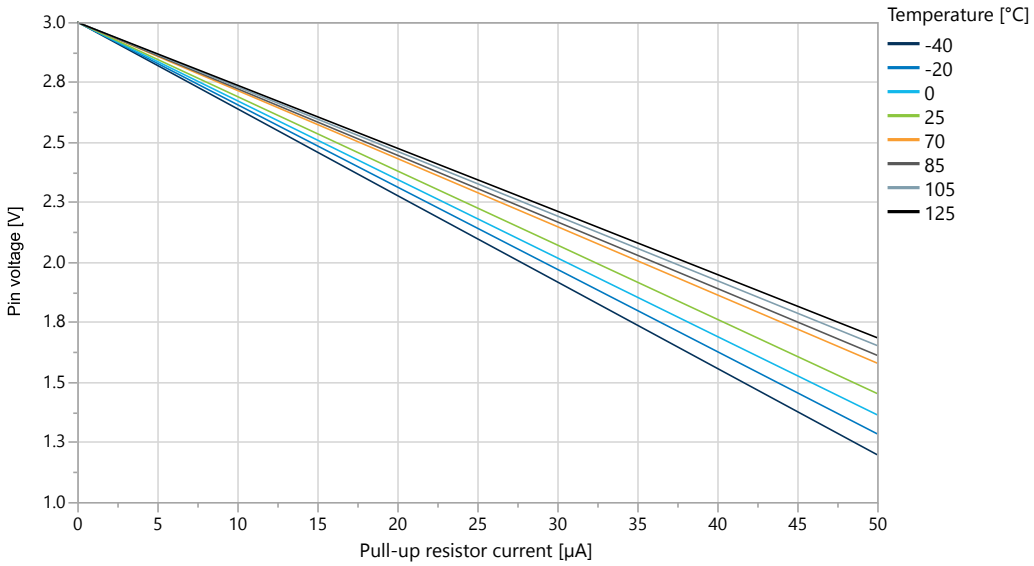


Figure 6-37. BOD Current vs. V_{DD} (Sampled BOD at 125 Hz)

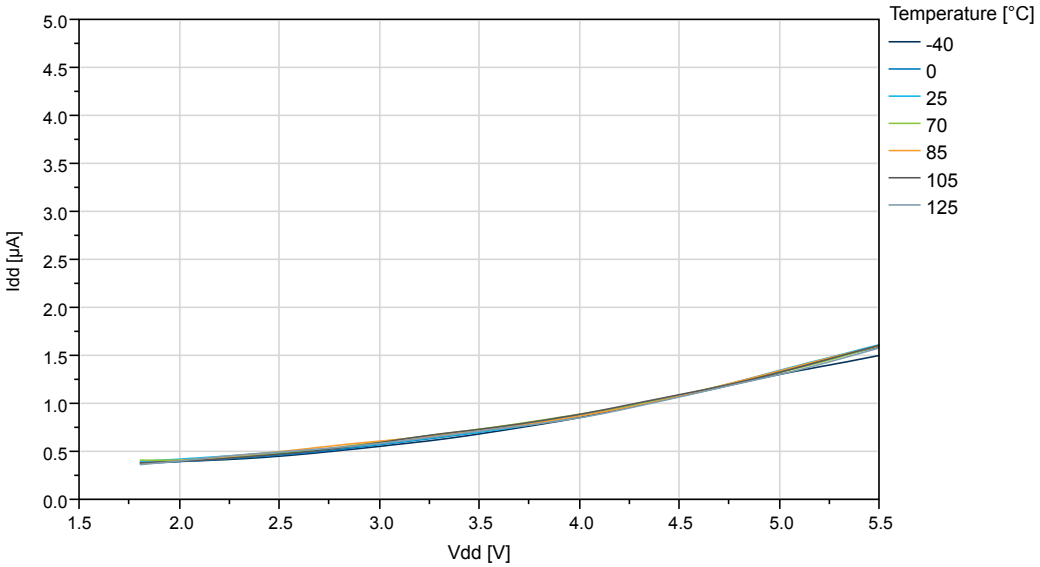
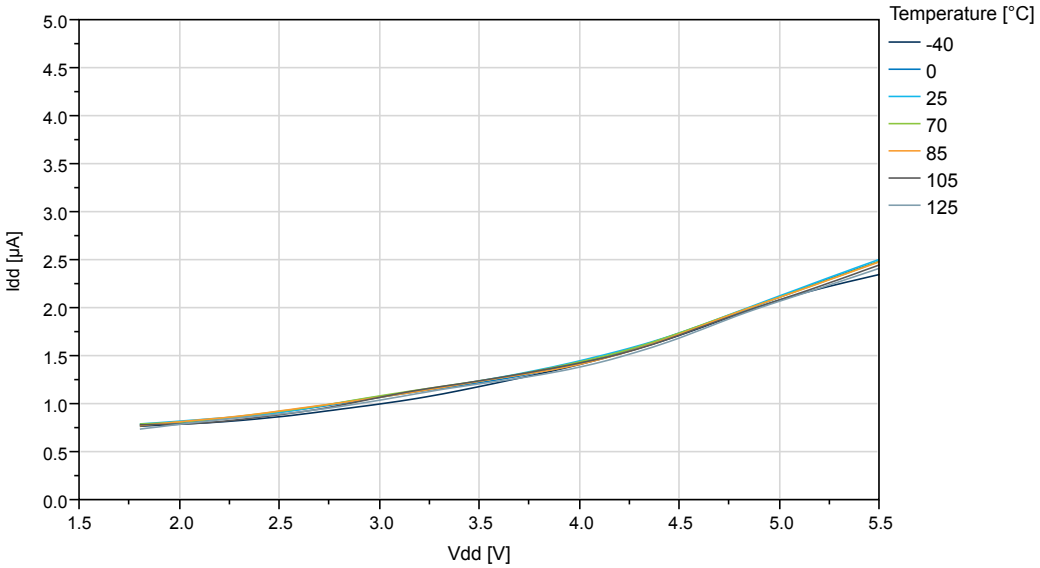


Figure 6-38. BOD Current vs. V_{DD} (Sampled BOD at 1 kHz)



BOD Threshold vs. Temperature

Figure 6-39. BOD Threshold vs. Temperature (Level 1.8V)

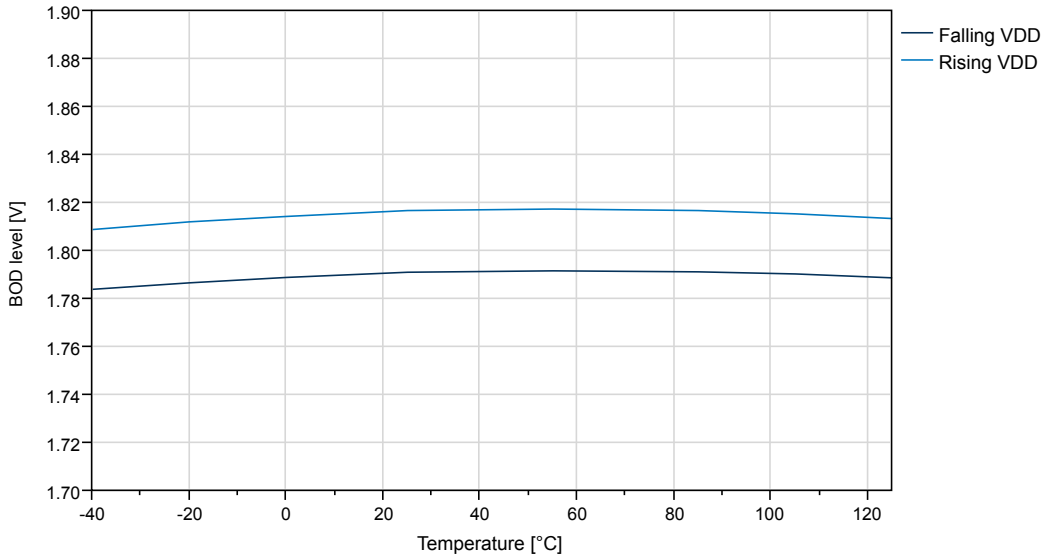


Figure 6-40. BOD Threshold vs. Temperature (Level 2.6V)

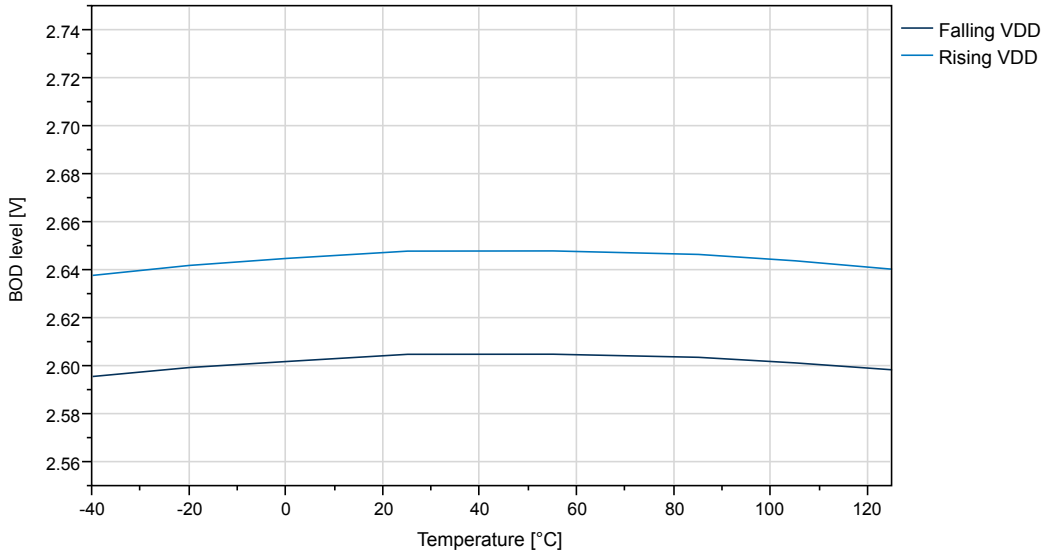


Figure 6-51. Offset Error vs. V_{ref} (V_{DD}=5.0V, f_{ADC}=115 ksps), REFSEL = Internal Reference

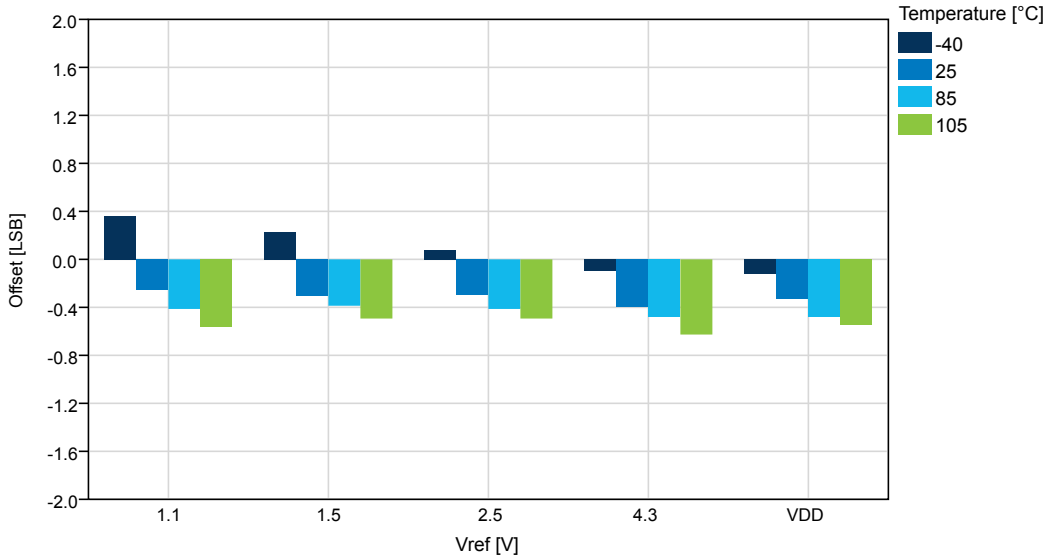


Figure 6-52. Absolute Accuracy vs. V_{DD} (f_{ADC}=115 ksps, T=25°C), REFSEL = External Reference

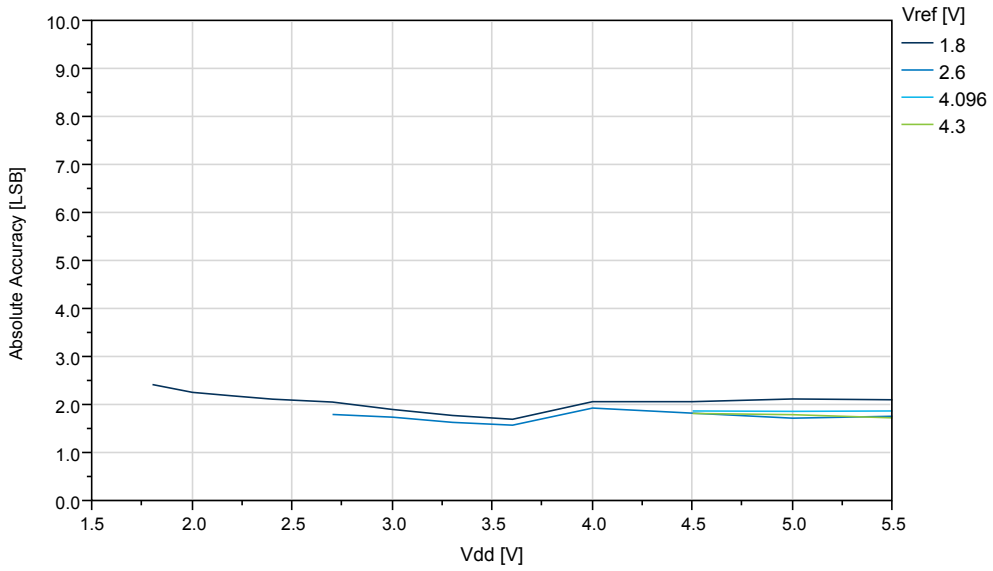
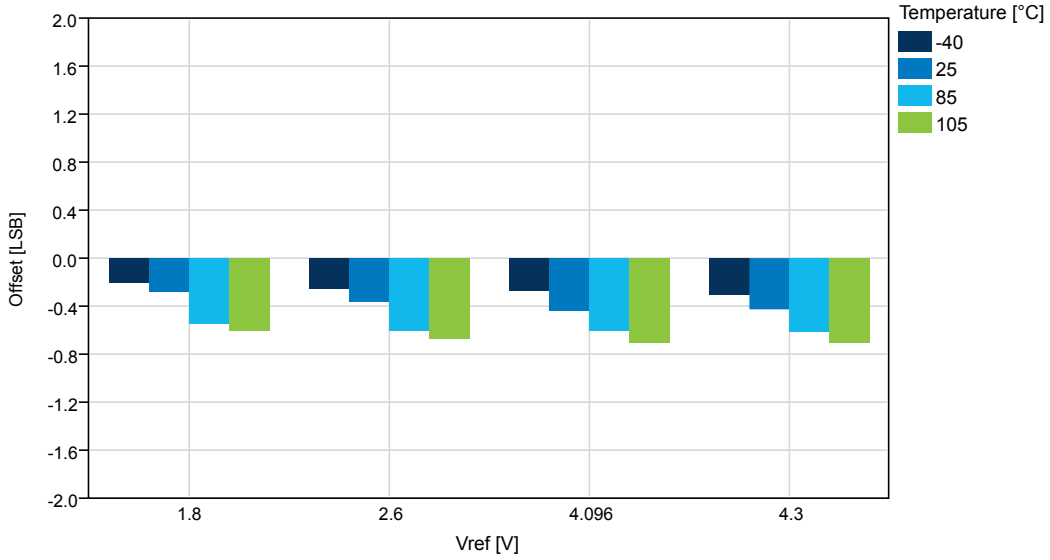


Figure 6-61. Offset vs. V_{REF} (V_{DD}=5.0V, f_{ADC}=115 ksps, REFSEL = External Reference)



6.6 AC Characteristics

Figure 6-62. Hysteresis vs. V_{CM} - 10 mV (V_{DD}=5V)

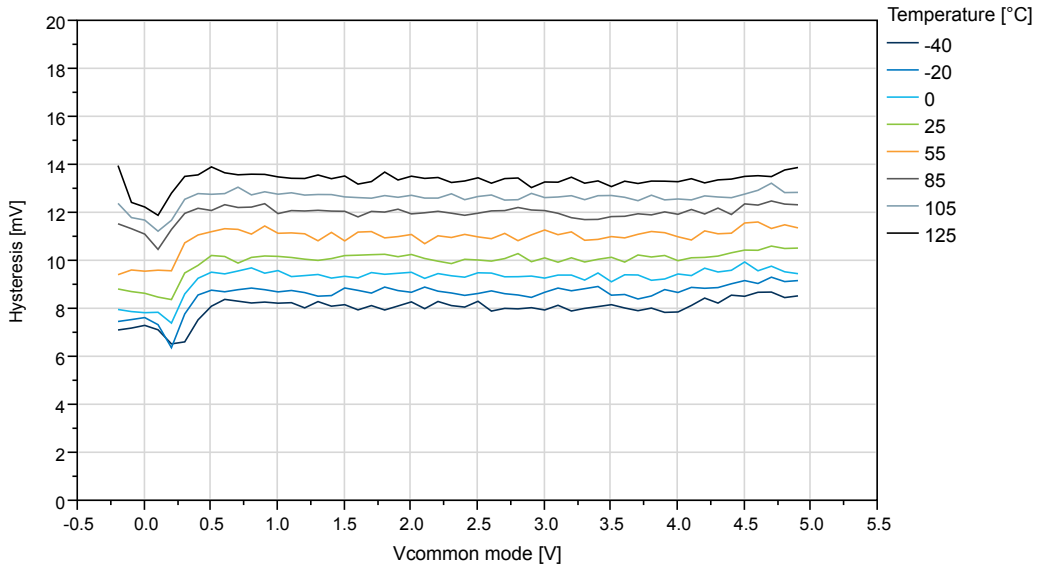


Figure 6-63. Hysteresis vs. V_{CM} - 10 mV to 50 mV (V_{DD}=5V, T=25°C)

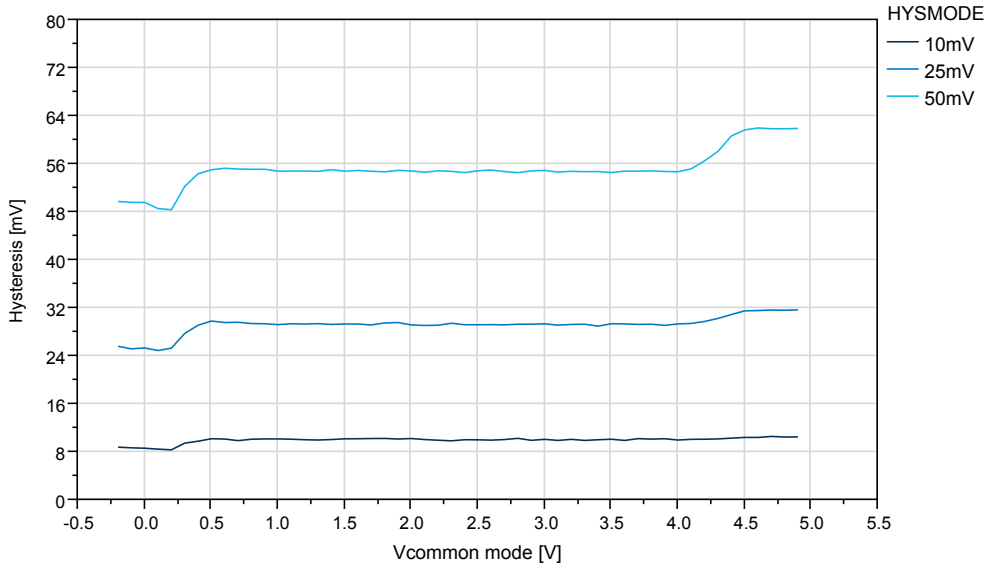
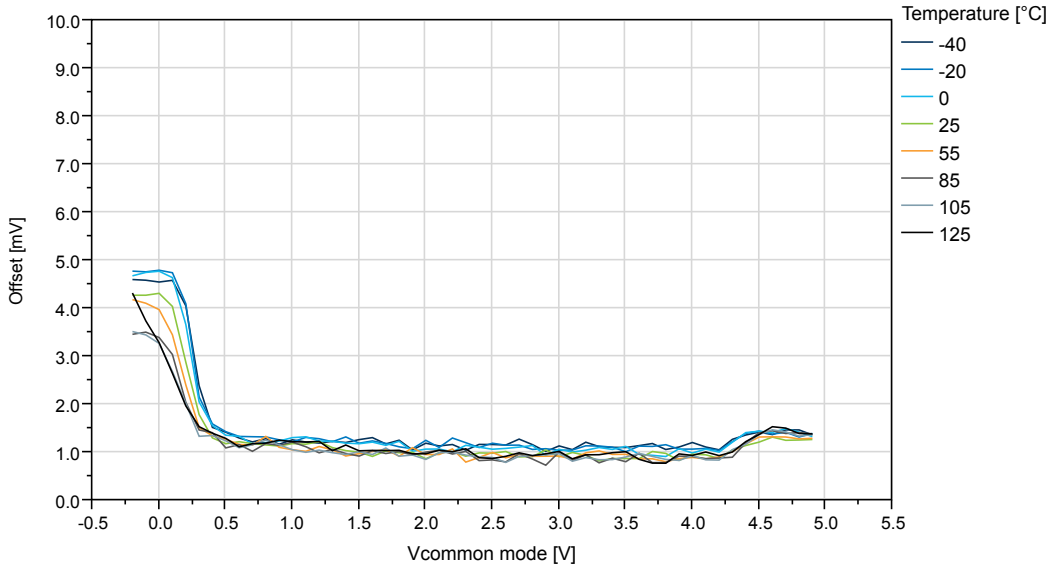


Figure 6-64. Offset vs. V_{CM} - 10 mV (V_{DD}=5V)



8. Conventions

8.1 Memory Size and Type

Table 8-1. Memory Size and Bit Rate

Symbol	Description
KB	kilobyte (2^{10} = 1024)
MB	megabyte (2^{20} = 1024*1024)
GB	gigabyte (2^{30} = 1024*1024*1024)
b	bit (binary '0' or '1')
B	byte (8 bits)
1 kbit/s	1,000 bit/s rate (not 1,024 bit/s)
1 Mbit/s	1,000,000 bit/s rate
1 Gbit/s	1,000,000,000 bit/s rate
word	16-bit

8.2 Frequency and Time

Table 8-2. Frequency and Time

Symbol	Description
kHz	1 kHz = 10^3 Hz = 1,000 Hz
KHz	1 KHz = 1,024 Hz, 32 KHz = 32,768 Hz
MHz	1 MHz = 10^6 Hz = 1,000,000 Hz
GHz	1 GHz = 10^9 Hz = 1,000,000,000 Hz
s	second
ms	millisecond
µs	microsecond
ns	nanosecond

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